

80V N-Channel Enhancement Mode MOSFET

Description

The AP100N08D uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

General Features

$V_{DS} = 80V$ $I_D = 100A$

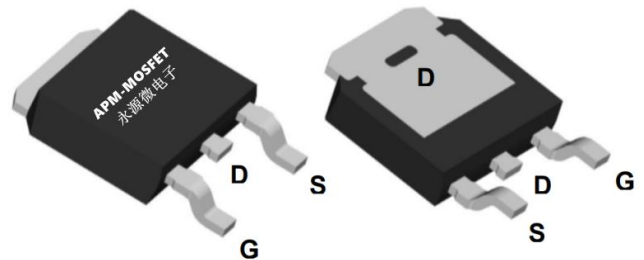
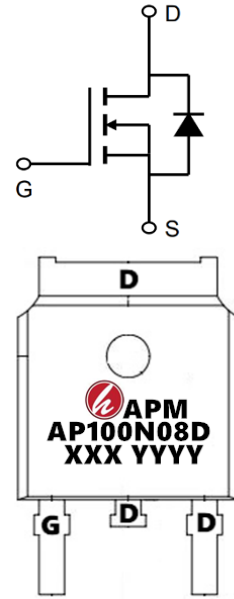
$R_{DS(ON)} < 6.8m\Omega$ $V_{GS}=10V$ (Type: $5.5m\Omega$)

Application

Battery protection

Load switch

Uninterruptible power supply



Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
AP100N08D	TO-252-3L	AP100N08D XXX YYYY	2500

Absolute Maximum Ratings ($T_C=25^\circ C$ unless otherwise noted)

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	80	V
V_{GS}	Gate-Source Voltage	± 20	V
$I_D@T_C=25^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^{1,6}$	100	A
$I_D@T_C=100^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^{1,6}$	60	A
I_{DM}	Pulsed Drain Current ²	400	A
E_{AS}	Single Pulse Avalanche Energy ³	506	mJ
$P_D@T_C=25^\circ C$	Total Power Dissipation ⁴	158	W
T_{STG}	Storage Temperature Range	-55 to 150	$^\circ C$
T_J	Operating Junction Temperature Range	-55 to 150	$^\circ C$
$R_{\theta JA}$	Thermal Resistance Junction-Ambient ¹	92	$^\circ C/W$
$R_{\theta JC}$	Thermal Resistance Junction-Case ¹	1.22	$^\circ C/W$

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Electrical Characteristics ($T_J=25^\circ\text{C}$, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BVDSS	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	80	92	---	V
RDS(ON)	Static Drain-Source On-Resistance ²	$V_{GS}=10V, I_D=50A$	---	5.5	6.8	m Ω
VGS(th)	Gate Threshold Voltage	$V_{GS}=V_{DS}, I_D=250\mu A$	2.0	3.0	4.0	V
IDSS	Drain-Source Leakage Current	$V_{DS}=80V, V_{GS}=0V, T_J=25^\circ\text{C}$	---	---	1	μA
		$V_{DS}=80V, V_{GS}=0V, T_J=55^\circ\text{C}$	---	---	5	
IGSS	Gate-Source Leakage Current	$V_{GS}=\pm 20V, V_{DS}=0V$	---	---	± 100	nA
gfs	Forward Transconductance	$V_{DS}=5V, I_D=20A$	---	75	---	S
R _g	Gate Resistance	$V_{DS}=0V, V_{GS}=0V, f=1\text{MHz}$	---	2.0	---	Ω
Q _g	Total Gate Charge (10V)	$V_{DS}=40V, V_{GS}=10V, I_D=20A$	---	56.6	---	nC
Q _{gs}	Gate-Source Charge		---	21.4	---	
Q _{gd}	Gate-Drain Charge		---	12.5	---	
Td(on)	Turn-On Delay Time	$V_{DD}=40V, V_{GS}=10V, R_G=3\Omega, I_D=20A$	---	17.3	---	ns
Tr	Rise Time		---	33	---	
Td(off)	Turn-Off Delay Time		---	38.9	---	
Tf	Fall Time		---	18.1	---	
Ciss	Input Capacitance	$V_{DS}=40V, V_{GS}=0V, f=1\text{MHz}$	---	3475	---	pF
Coss	Output Capacitance		---	770	---	
Crss	Reverse Transfer Capacitance		---	25	---	
IS	Continuous Source Current ^{1,5}	$V_G=V_D=0V$, Force Current	---	---	100	A
VSD	Diode Forward Voltage ²	$V_{GS}=0V, I_S=A, T_J=25^\circ\text{C}$	---	0.9	1.3	V
trr	Reverse Recovery Time	$I_F=20A, dI/dt=100A/\mu s, T_J=25^\circ\text{C}$	---	68	---	nS
Q _{rr}	Reverse Recovery Charge		---	66	---	nC

Note :

- 1、The data tested by surface mounted on a 1 inch² FR-4 board with 20Z copper.
- 2、The data tested by pulsed , pulse width .The EAS data shows Max. rating .
- 3、The test cond $\cong 300\mu s$ duty cycle $\cong 2\%$, duty cycle ition is $V_{DD}=64V, V_{GS}=10V, L=0.1mH, I_{AS}=40A$
- 4、The power dissipation is limited by 175°C junction temperature
- 5、The data is theoretically the same as ID and IDM , in real applications , should be limited by total power dissipation.

Typical Characteristics

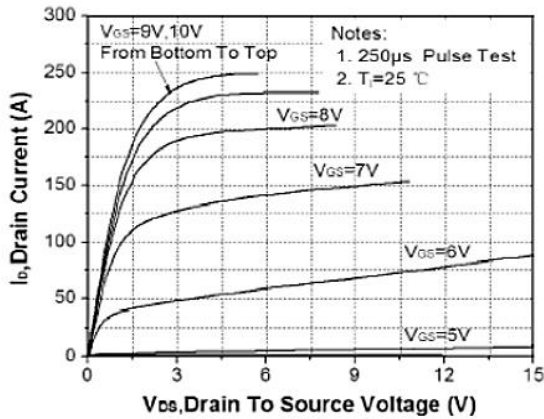


Figure 1. Typ. Output Characteristics ($T_j=25^\circ\text{C}$)

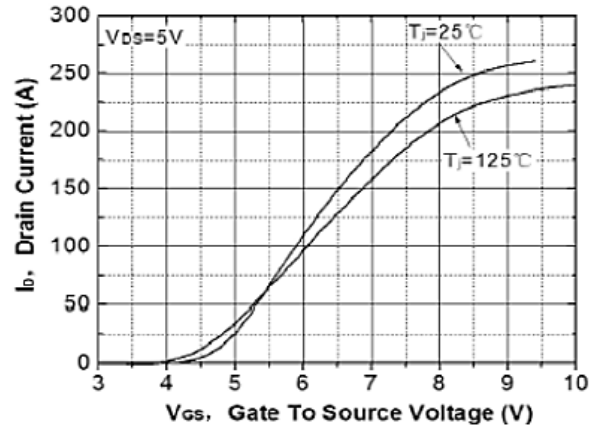


Figure 2. Transfer Characteristics

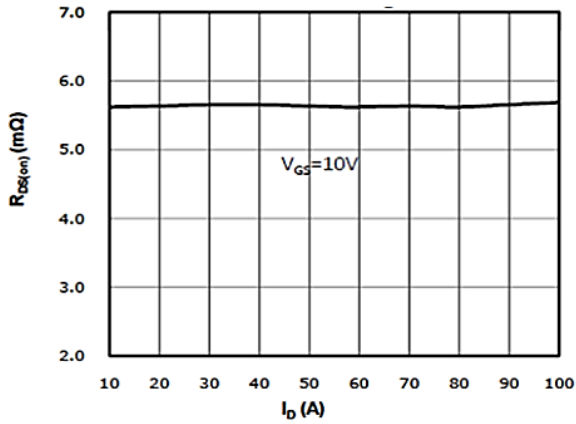


Figure 3. On-Resistance vs. Drain Current and Gate Voltage Figure

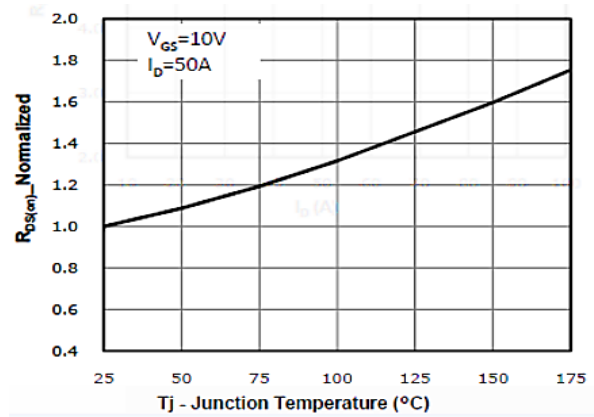


Figure 4. On-Resistance vs. Junction Temperature

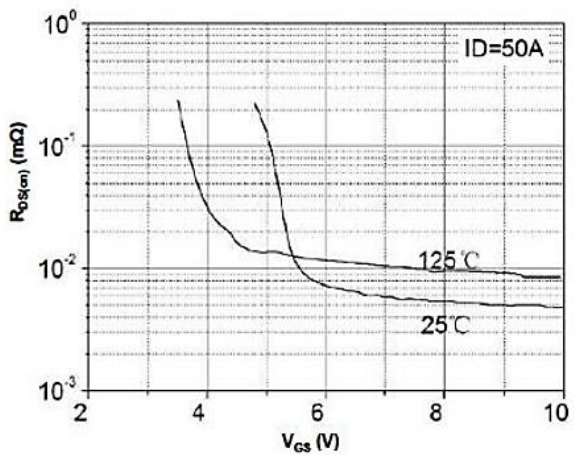


Figure 5. On-Resistance vs. Gate-Source Voltage

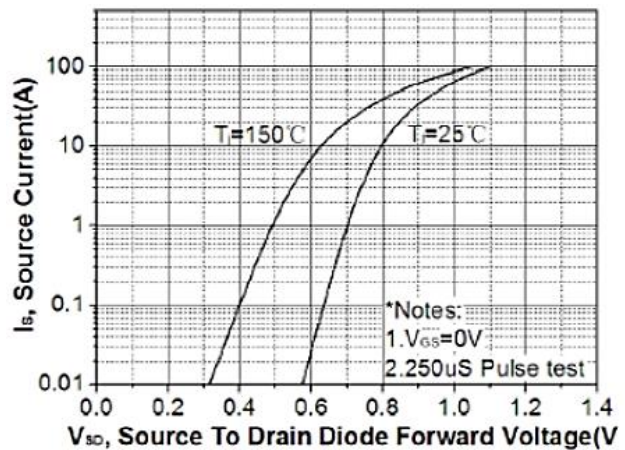
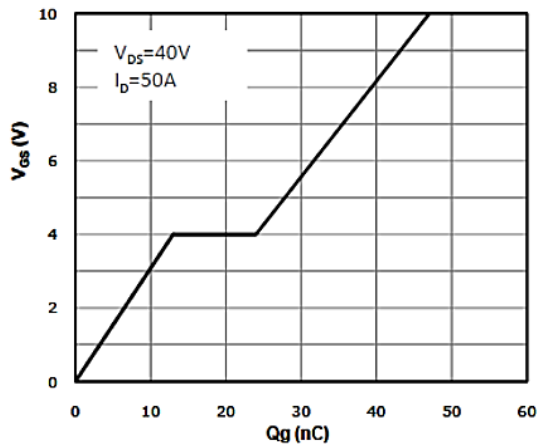
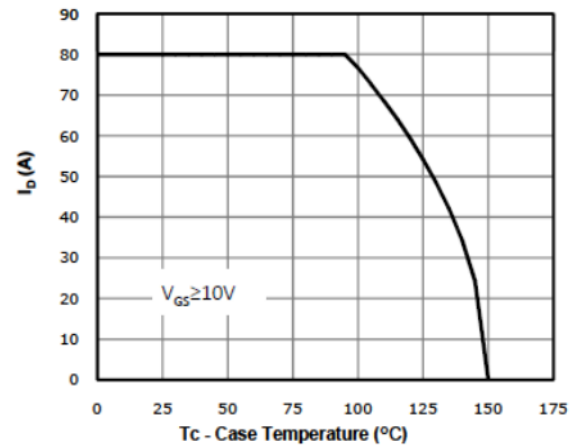
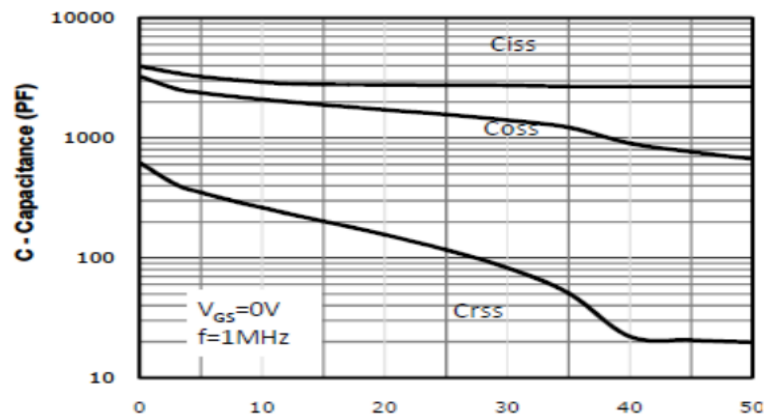
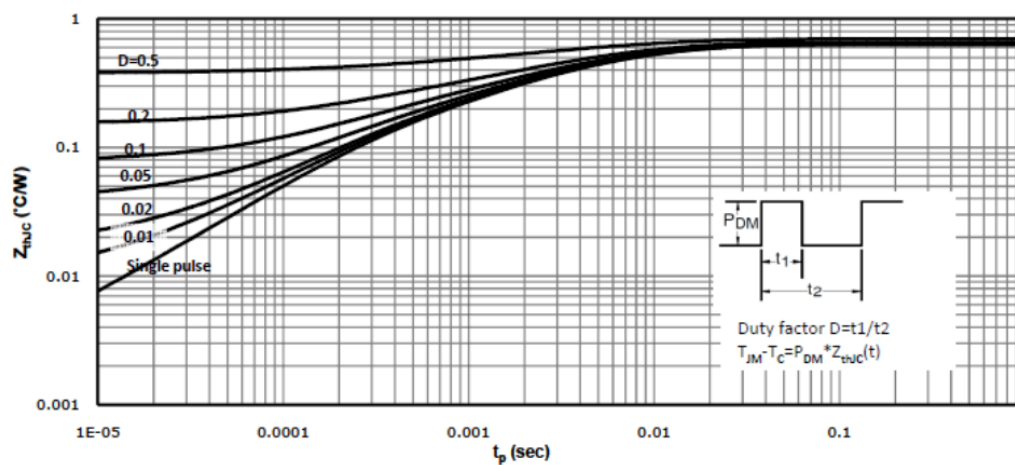
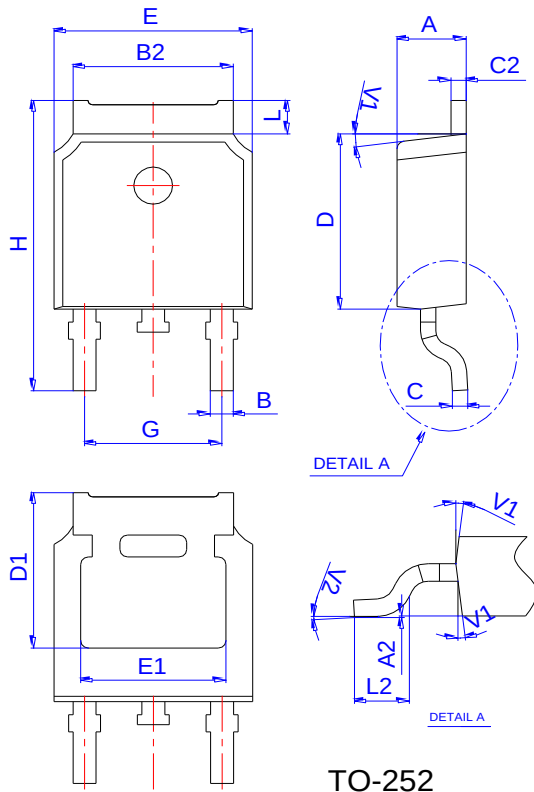


Figure 6 . Body-Diode Characteristics

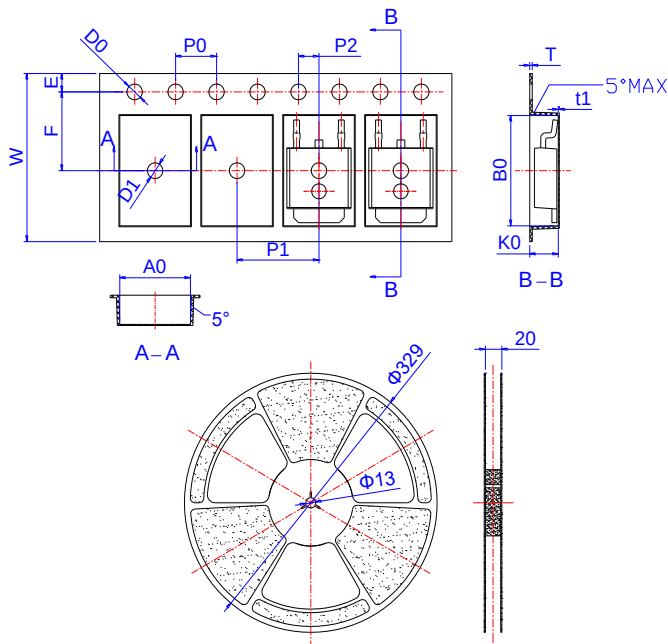
**Figure 7. Gate-Charge Characteristics****Figure 8. Drain Current Derating****Figure 9: Normalized Maximum Transient Thermal Impedance****Figure 10. Capacitance Characteristics**

Package Mechanical Data: TO-252-3L



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	2.10		2.50	0.083		0.098
A2	0		0.10	0		0.004
B	0.66		0.86	0.026		0.034
B2	5.18		5.48	0.202		0.216
C	0.40		0.60	0.016		0.024
C2	0.44		0.58	0.017		0.023
D	5.90		6.30	0.232		0.248
D1	5.30REF			0.209REF		
E	6.40		6.80	0.252		0.268
E1	4.63			0.182		
G	4.47		4.67	0.176		0.184
H	9.50		10.70	0.374		0.421
L	1.09		1.21	0.043		0.048
L2	1.35		1.65	0.053		0.065
V1		7°			7°	
V2	0°		6°	0°		6°

Reel Specification



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
W	15.90	16.00	16.10	0.626	0.630	0.634
E	1.65	1.75	1.85	0.065	0.069	0.073
F	7.40	7.50	7.60	0.291	0.295	0.299
D0	1.40	1.50	1.60	0.055	0.059	0.063
D1	1.40	1.50	1.60	0.055	0.059	0.063
P0	3.90	4.00	4.10	0.154	0.157	0.161
P1	7.90	8.00	8.10	0.311	0.315	0.319
P2	1.90	2.00	2.10	0.075	0.079	0.083
A0	6.85	6.90	7.00	0.270	0.271	0.276
B0	10.45	10.50	10.60	0.411	0.413	0.417
K0	2.68	2.78	2.88	0.105	0.109	0.113
T	0.24		0.27	0.009		0.011
t1	0.10			0.004		
10P0	39.80	40.00	40.20	1.567	1.575	1.583

80V N-Channel Enhancement Mode MOSFET**Attention**

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